

# PATENT ABSTRACTS OF JAPAN

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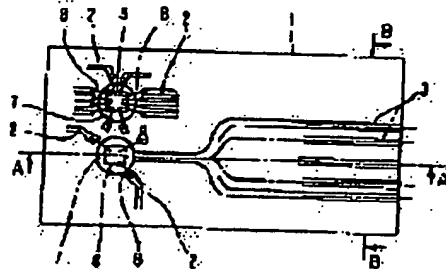
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## (54) OPTICAL CIRCUIT AND ELECTRIC CIRCUIT MIXED SUBSTRATE

(57)Abstract:

**PURPOSE:** To obtain the optical circuit and electric circuit mixed substrate which facilitates size reduction, high-speed processing of light signals, and variation in light signal wavelength and is superior in economy by mounting respective functional elements on the substrate in a bare chip state.

**CONSTITUTION:** An electric circuit 2 and an optical circuit 3 are formed on the surface of a semiconductor substrate 1 such as an Si substrate and a light emitting element such as an LED (or light receiving element such as a PD) and a communication control element 5 are mounted in a bare chip state. The electric circuit 2 is formed of aluminum wiring, etc., formed in specific pattern by, for example, a lift-off. The optical circuit 3, on the other hand, is formed by forming grooves in, for example, the substrate 1 by etching, etc., and embedding an organic material such as polyimide in the grooves by spin coating, etc. Further, the light emitting element 3 and communication control element 5 are fixed in a recessed part 7 formed at a specific position on the substrate 1 and the electrodes of the light emitting element 4 and communication control element 5 and the electric circuit 2 are connected with a bonding wire (or TAB lead) 8.



## LEGAL STATUS

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